

monitoring and control functionality.

Dual Rx Video SFPs

*T&R = Tape and reel.* \**EP = Exposed pad.*

## *DS1877*

### *SFP Controller for Dual Rx Interface*

#### *General Description*

 *Applications*

 *Ordering Information*

The DS1877 controls and monitors all functions for SFF, SFP, and SFP+ modules including all SFF-8472 functionality. The device supports all LOS functions for two receivers, and continually monitors for LOS of either channel. Four ADC channels monitor V<sub>CC</sub>, temperature, and two differential external monitor inputs that can be used to meet all monitoring requirements. Two digitalto-analog converter (DAC) outputs with temperatureindexed lookup tables (LUTs) are available for additional

SFF, SFP, and SFP+ Transceiver Modules

PART TEMP RANGE PIN-PACKAGE

+*Denotes a lead(Pb)-free/RoHS-compliant package.*

 $DS1877T+ -40^{\circ}C$  to +95°C 28 TQFN-EP\*  $DS1877T+TRR$   $-40^{\circ}$ C to  $+95^{\circ}$ C  $-28$  TQFN-EP\*  *Features*

- ◆ Meets All SFF-8472 Control and Monitoring **Requirements**
- ◆ Four Analog Monitor Channels: Temperature, V<sub>CC</sub>, RSSI1, RSSI2 RSSI1 and RSSI2 Support Internal and External **Calibration** Differential Input Common-Mode Range from GND to VCC Scalable Dynamic Range Internal Direct-to-Digital Temperature Sensor Alarm and Warning Flags for All Monitored Channels
- ◆ Two 10-Bit Delta-Sigma Outputs Each Controlled by 72-Entry Temperature LUT
- ◆ Digital I/O Pins: Four Inputs, Four Outputs
- ♦ Comprehensive Loss-of-Signal (LOS) Detection System
- ◆ Flexible, Two-Level Password Scheme Provides Three Levels of Security
- ♦ 120 Bytes of Password-1 Protected Memory
- ♦ 128 Bytes of Password-2 Protected Memory in Main Device Address
- ♦ 256 Additional Bytes Located at A0h Slave Address
- ♦ Receiver 1 is Accessed at A2h Slave Address
- ♦ Receiver 2 is Accessed at B2h Slave Address
- $\triangle$  I<sup>2</sup>C-Compatible Interface
- $\div$  +2.85V to +3.9V Operating Voltage Range
- $\triangle$  -40°C to +95°C Operating Temperature Range
- ◆ 28-Pin TQFN (5mm x 5mm x 0.75mm) Package



## *SFP Controller for Dual Rx Interface*



#### LIST OF FIGURES



#### LIST OF TABLES



### *SFP Controller for Dual Rx Interface*

#### <span id="page-4-0"></span>ABSOLUTE MAXIMUM RATINGS

Voltage Range on RSSI1, RSSI2, INX, LOS1,

and LOS2 Pins Relative to Ground......-0.5V to  $(V_{CC} + 0.5V)^*$ Voltage Range on VCC, SDA, SCL, OUTX, FAULT,

 RSELOUT, and LOSOUT Pins Relative to Ground....-0.5V to +6V Continuous Power Dissipation

28-Pin TQFN (derate 34.5mW/°C) above +70°C....2758.6mW



\**Subject to not exceeding +6V.*

*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

#### RECOMMENDED OPERATING CONDITIONS

 $(T_A = -40^{\circ}$ C to  $+95^{\circ}$ C, unless otherwise noted.)



#### DC ELECTRICAL CHARACTERISTICS

(V<sub>CC</sub> = +2.85V to +3.9V,  $T_A$  = -40°C to +95°C, unless otherwise noted.)



### <span id="page-5-0"></span>DAC1, DAC2 ELECTRICAL CHARACTERISTICS

(V<sub>CC</sub> =  $+2.85V$  to  $+3.9V$ , T<sub>A</sub> = -40°C to  $+95°C$ , unless otherwise noted.)



#### ANALOG VOLTAGE MONITORING CHARACTERISTICS

(V<sub>CC</sub> =  $+2.85V$  to  $+3.9V$ , T<sub>A</sub> =  $-40^{\circ}$ C to  $+95^{\circ}$ C, unless otherwise noted.)



#### AC ELECTRICAL CHARACTERISTICS

(V<sub>CC</sub> =  $+2.85V$  to  $+3.9V$ , T<sub>A</sub> = -40°C to  $+95^{\circ}$ C, unless otherwise noted.)



### *SFP Controller for Dual Rx Interface*

#### <span id="page-6-0"></span>ANALOG QUICK-TRIP CHARACTERISTICS

(V<sub>CC</sub> =  $+2.85V$  to  $+3.9V$ , T<sub>A</sub> = -40°C to  $+95^{\circ}$ C, unless otherwise noted.)



#### QUICK-TRIP TIMING CHARACTERISTICS

(V<sub>CC</sub> =  $+2.85V$  to  $+3.9V$ , T<sub>A</sub> = -40°C to  $+95^{\circ}$ C, unless otherwise noted.)



#### DIGITAL THERMOMETER CHARACTERISTICS

(V<sub>CC</sub> =  $+2.85V$  to  $+3.9V$ , T<sub>A</sub> = -40°C to  $+95^{\circ}$ C, unless otherwise noted.)



#### I2C AC ELECTRICAL CHARACTERISTICS

(V<sub>CC</sub> = +2.85V to +3.9V, T<sub>A</sub> = -40°C to +95°C, unless otherwise noted. Timing is referenced to V<sub>IL(MAX)</sub> and V<sub>IH(MIN)</sub>.) (Figure 12)



#### <span id="page-7-0"></span>NONVOLATILE MEMORY CHARACTERISTICS

 $(V_{\text{CC}} = +2.85V \text{ to } +3.9V, \text{ unless otherwise noted.})$ 



Note 1: All voltages are referenced to ground. Current into the IC is positive, and current out of the IC is negative.

Note 2: Inputs are at supply rail. Outputs are not loaded.

Note 3: This parameter is guaranteed by design.

Note 4: Full-scale is user programmable.

Note 5: A temperature conversion is completed and the DAC values are recalled from the LUTs and V<sub>CC</sub> has been measured to be above the VCC LO alarm, if the VCC LO alarm is enabled.

Note 6: This specification is the time it takes from RSSI1\_ and RSSI2\_ voltage falling below the LLOS\_ trip threshold to LOSOUT asserted high.

Note 7: This specification is the time it takes from RSSI1\_ and RSSI2\_ voltage rising above the HLOS\_ trip threshold to LOSOUT asserted high.

Note 8: I<sup>2</sup>C interface timing shown is for fast-mode (400kHz) operation. This device is also backward compatible with I<sup>2</sup>C standard mode.

Note 9: C<sub>B</sub>—Total capacitance of one bus line in pF.

Note 10: EEPROM write begins after a STOP condition occurs.

<span id="page-8-0"></span>(VCC =  $+3.3V$ , TA =  $+25^{\circ}$ C, unless otherwise noted.)





 *Typical Operating Characteristics*



#### DAC1/DAC2 INL









<span id="page-9-0"></span>RSSI1N TOP VIEW DAC2  $\mathbb{S}^0$ DAC1 GND 2014 0 19 19 19 10 11 12 12 13 14 15 16 17 18 17 18 17 18 17 18 17 18 18 18 19 10 11 12 13 14 15 16 17 18 18 1 VCC dNS\_ 21. The control of the N.C. 21 | 20 | 19 | 18 | 17 | 16 | 15 REFIN 22 14 RSSI1P N.C. 23 13 RSSI2N N.C. 12 RSSI2P 24 11 N.C. N.C. 25 *DS1877*  $\rm V_{CC}$ 10 DNC 26 LOSOUT Î RSEL 27 9 \*EP **+** OUTX 28 8 GND 1 | | 2 | | 3 | | 4 | | 5 | | 6 | | 7 RSELOUT LOS2 SDA LOS1 INX SCL FAULT **THIN QFN (5mm × 5mm × 0.8mm)** \*EXPOSED PAD.





#### *Pin Description*

 *Pin Configuration*

 *Block Diagram*

<span id="page-10-0"></span>

 *Typical Operating Circuit*

<span id="page-11-0"></span>

#### *Detailed Description*

<span id="page-12-0"></span>The DS1877 integrates the control and monitoring functionality required in an SFP or SFP+ system. The device is specifically designed for a dual-receiver SFP module. Key components of the device are shown in the *Block Diagram* and described in subsequent sections.

#### *DACs During Power-Up*

On power-up, the device sets the DACs to high impedance. After time t<sub>INIT</sub>, the DACs are set to an initial condition set in EEPROM. After a temperature conversion is completed and if the VCC LO alarm is enabled, an additional VCC conversion above the customer-defined VCC LO alarm level is required before the DACs are updated with the value determined by the temperature conversion and the DAC LUT. See Figure 1.

#### *Quick-Trip Timing*

As shown in Figure 2, the device's input comparator is shared between two LOS comparisons. The comparator polls the alarms in a multiplexed sequence. The comparator checks the LOS (RSSI1\_ and RSSI2\_) signals against the internal reference. Depending on the results of the comparison, the corresponding alarms and warnings are asserted or deasserted. Any QT alarm that is detected by default remains active until a subsequent comparator sample shows that the condition no longer exists.

#### Table 1. Acronyms





*Figure 1. Power-Up Timing*



*Figure 2. Quick-Trip Sample Timing*

#### *Monitors and Fault Detection Monitors*

<span id="page-13-0"></span>Monitoring functions on the device include two QT comparators and four ADC channels. This monitoring combined with the alarm enables (Table 01h/05h) determines when/if the device triggers the FAULT and/or LOSOUT outputs. All the monitoring levels and interrupt masks are user programmable.

#### *Two Quick-Trip Monitors and Alarms*

Two quick-trip monitors are provided that monitor the following:

- 1) Loss of signal 1 (LOS1 LO)
- 2) Loss of signal 2 (LOS2 LO)

The LOS\_ LO QTs compare the RSSI\_ input against its threshold setting to determine if the present received power is below the specification. The LOS\_ LO QT can be used to set the LOSOUT pin.

#### *Four ADC Monitors and Alarms*

The ADC monitors 4 channels that measure temperature (internal temp sensor), VCC, RSSI1, and RSSI2 using an analog multiplexer to measure them round-robin with a single ADC (see the *ADC Timing* section). The 3V channels have a customer-programmable full-scale range, and all channels have a customer-programmable offset value that is factory programmed to a default value (see Table 2). Additionally, RSSI1 and RSSI2 can right-shift results by up to 7 bits before the results are compared to alarm thresholds or read over the I2C bus. This allows customers with specified ADC ranges to calibrate the ADC full scale to a factor of 1/2n of their specified range to measure small signals. The device can then right-shift the results by n bits to maintain the bit weight of their specification (see the *Right-Shifting ADC Result* section).

The ADC results (after right-shifting, if used) are compared to the alarm and warning thresholds after each conversion, and the corresponding alarms are set that can be used to trigger the FAULT output. These ADC thresholds are user programmable, as are the masking registers that can be used to prevent the alarms from triggering the FAULT output.

#### *ADC Timing*

There are four analog channels that are digitized in a round-robin fashion in the order as shown in Figure 3. The total time required to convert all 4 channels is tRR (see the *Analog Voltage Monitoring Characteristics* for details).

#### *Right-Shifting ADC Result*

If the weighting of the ADC digital reading must conform to a predetermined full-scale (PFS) value defined by a standard's specification (e.g., SFF-8472), then rightshifting can be used to adjust the PFS analog measurement range while maintaining the weighting of the ADC results. The device's range is wide enough to cover all requirements; when the maximum input value is  $\leq 1/2$ the FS value, right-shifting can be used to obtain greater accuracy. For instance, the maximum voltage might be 1/8 the specified PFS value, so only 1/8 of the converter's range is effective over this range. An alternative is to calibrate the ADC's full-scale range to 1/8 the readable PFS value and use a right-shift value of 3. With this implementation, the resolution of the measurement is increased by







*Figure 3. ADC Round-Robin Timing*

### *SFP Controller for Dual Rx Interface*

<span id="page-14-0"></span>a factor of 8, and because the result is digitally divided by 8 by right-shifting, the bit weight of the measurement still meets the standard's specification (i.e., SFF-8472).

The right-shift operation on the ADC result is carried out based on the contents of right-shift control registers (Table 02h, Registers 8Eh–8Fh) in EEPROM. Two analog channels—RSSI1 and RSSI2—each have 3 bits allocated to set the number of right-shifts. Up to seven right-shift operations are allowed and are executed as a part of every conversion before the results are compared to the high and low alarm levels, or loaded into their corresponding measurement registers (Lower Memory, Registers 64h to 6Bh). This is true during the setup of internal calibration as well as during subsequent data conversions.

#### *Differential RSSI1/RSSI2 Inputs*

The device offers fully differential inputs for RSSI1 and RSSI2. This enables high-side monitoring of RSSI, as shown in Figure 4. It also reduces board complexity by



*Figure 4. RSSI1/RSSI2 Differential Input for High-Side RSSI*

Table 3. RSSI1/RSSI2 Configuration Registers

eliminating the need for a high-side differential amplifier or a current mirror.

#### *Enhanced RSSI Monitoring (Dual-Range Functionality)*

The device offers a feature to improve the accuracy and range of RSSI1/RSSI2, which is most commonly used for monitoring RSSI. Using a traditional input, the RSSI measurement accuracy can be increased at the cost of reduced input signal swing. The device eliminates this trade-off by offering "dual-range" calibration on the RSSI1/RSSI2 channels. The dual-range calibration can operate in two modes: crossover enabled and crossover disabled. Dual-range operation is enabled by default (factory programmed in EEPROM). However, it can easily be disabled by the RSSIn\_FC and RSSIn\_FF bits (where n can be 1 or 2) in 8Dh, Table 02h.

Dual-range functionality consists of two ADC modes of operation: fine mode and coarse mode. Each mode is calibrated for a unique transfer function, hence the term, dual range. Table 3 highlights the registers related to RSSI1/RSSI2. Fine mode is calibrated using the gain, offset, and right-shifting registers at locations shown in Table 3, and is ideal for relatively small analog-input voltages. Coarse mode is automatically switched to when the input exceeds a threshold. Coarse mode is calibrated using different gain and offset registers from fine mode. The gain and offset registers for coarse mode are also shown in Table 3. Additional information for each of the registers can be found in the memory map (Figure 14).



<span id="page-15-0"></span>Dual-range operation is transparent to the end user. The results of RSSI1/RSSI2 ADCs are still stored/reported in the same memory locations (68h*−*69h, Lower Memory) regardless of whether the conversion was performed in fine mode or coarse mode. The RSSIR bit indicates whether a fine or coarse conversion generated the digital result.

When the device is powered up, ADCs begin in a roundrobin fashion. Every RSSI1/RSSI2 time slice begins with a fine mode ADC (using fine mode's gain, offset, and right-shifting settings). If the value is too large for a fine conversion, a coarse conversion is performed and the result is reported. The coarse-mode conversion is performed using the coarse gain and offset settings. The intersection between coarse and fine depends on the crossover mode used.

The RSSIn\_FC and RSSIn\_FF bits are used to force fine-mode or coarse-mode conversions or to disable the dual-range functionality. Dual-range functionality is enabled by default (both RSSIn\_FC and RSSIn\_FF are factory programmed to 0 in EEPROM). Dual-range functionality can be disabled by setting RSSIn\_FC to 0 and RSSIn FF to 1. These bits are also useful when calibrating RSSI1/RSSI2. See the register descriptions and memory map for additional information.

#### *Crossover Enabled*

For systems with a nonlinear relationship between the ADC input and desired ADC result, the mode should be set to crossover enabled (Figure 5). The RSSI measurement of an APD receiver is one such application. Using the crossover-enabled mode allows a piecewise linear approximation of the nonlinear response of the APD's gain factor. The crossover point is the value where the fine and coarse ranges intersect. The ADC result transitions between the fine and coarse ranges as defined by the XOVER registers. Right-shifting, slope adjustment, and offset are configurable for both the fine and coarse ranges. The XOVER1/XOVER2 FINE registers determine the maximum results returned by the fine ADC conversions before right-shifting. The XOVER1/ XOVER2 COARSE registers determine the minimum results returned by coarse ADC conversions before right-shifting.

#### *Crossover Disabled*

The crossover-disabled mode is intended for systems with a linear relationship between the RSSI1/RSSI2 input and the desired ADC result. The ADC result transitions between the fine and coarse ranges with hysteresis, as shown in Figure 6.

In crossover-disabled mode, the thresholds between coarse and fine mode are a function of the number of right-shifts being used. With the use of right-shifting, the fine-mode full scale is programmed to (1/2n) of the coarse-mode full scale. The device now automatically ranges to choose the range that gives the best resolution for the measurement. Table 4 shows the threshold values for each possible number of right-shifts.

#### *Low-Voltage Operation*

The device contains two power-on reset (POR) levels. The lower level is a digital POR (POD) and the higher level is an analog POR (POA). At startup, before the supply voltage rises above POA, the outputs are disabled, all SRAM locations are set to their defaults, shadowed EEPROM (SEE) locations are zero, and all analog circuitry is disabled. When  $V_{CC}$  reaches POA, the SEE is recalled, and the analog circuitry is enabled. While VCC remains above POA, the device is in its normal operating state, and it responds based on its nonvolatile configuration. If during operation VCC falls below POA, but is still above POD, the SRAM retains the SEE settings from the first SEE recall, but the device analog is shut down and the outputs disabled. If the supply voltage recovers back above POA, the device immediately resumes normal operation. If the supply voltage falls below POD, the device SRAM is placed in its default state and another SEE recall is required to reload the nonvolatile settings. The EEPROM recall occurs the next time  $V_{CC}$  next exceeds POA. Figure 7 shows the sequence of events as the voltage varies.

#### Table 4. RSSI1/RSSI2 Hysteresis Threshold Values



\**This is the minimum reported coarse-mode conversion.*

## *SFP Controller for Dual Rx Interface*

<span id="page-16-0"></span>

*Figure 5. Crossover Enabled*



*Figure 6. Crossover Disabled*



*Figure 7. Low-Voltage Operation*

<span id="page-17-0"></span>Any time V<sub>CC</sub> is above POD, the I<sup>2</sup>C interface can be used to determine if VCC is below the POA level. This is accomplished by checking the RDYB bit in the STATUS byte (Lower Memory, Register 6Eh). RDYB is set when VCC is below POA; when VCC rises above POA, RDYB is timed (within  $500\mu s$ ) to go to 0, at which point the part is fully functional.

For all device addresses sourced from EEPROM (Table 02h, Register 8Bh), the default device address is A2h until V<sub>CC</sub> exceeds POA, allowing the device address to be recalled from the EEPROM.

#### *Delta-Sigma Outputs*

The device's delta-sigma outputs are 10 bits. For illustrative purposes, a 3-bit example is provided in Figure 8.



*Figure 8. Recommended RC Filter for DAC Outputs*

Each possible output of this 3-bit delta-sigma DAC is provided in Figure 9.

In LUT mode the DACs are each controlled by an LUT with high-temperature resolution and an OFFSET LUT with lower temperature resolution. The high-resolution LUTs each have 2°C resolutions. The OFFSET LUTs are located in the upper eight registers (F8h–FFh, Table 04h) of the table containing each high-resolution LUT. The DAC values are determined as follows:

DAC value = DAC LUT +  $4 \times$  (DAC OFFSET LUT)

An example calculation for DAC1 is as follows:

Assumptions:

- 1) Temperature is  $+43^{\circ}$ C
- 2) Table 04h (DAC OFFSET LUT), Register FCh = 2Ah
- 3) Table 04h (DAC LUT), Register AAh = 7Bh

Because the temperature is  $+43^{\circ}$ C, the DAC LUT index is AAh and the DAC1 OFFSET LUT index is FCh.

$$
DAC1 = 7Bh + 4 \times 2Ah = 123h = 291
$$

When temperature controlled, the DACs are updated after each temperature conversion. See Figure 10.

The reference input, REFIN, is the supply voltage for the output buffer of all the DACs. The voltage connected to REFIN must be able to support the edge rate requirements of the delta-sigma outputs. In a typical application, a 0.1µF capacitor should be connected between REFIN and ground.



*Figure 9. 3-Bit (8-Position) Delta-Sigma Example*

### *SFP Controller for Dual Rx Interface*

<span id="page-18-0"></span>

*Figure 10. DAC Offset LUTs*



*Figure 11. Logic Diagram*

#### **DAC OFFSET LUTs (04h)[A2h/B2h] EIGHT REGISTERS PER DAC**



#### *Digital I/O Pins*

Four digital input pins and four digital output pins are provided for monitoring and control.

#### *LOS1, LOS2, and LOSOUT*

When LOSC<sub>\_</sub> = 0 (Table 02h, Register 8Ah), the LOS\_ pin is used to convert a standard comparator output for LOS to an open-collector output. The output of the mux can be read in the STATUS register (Lower Memory, Register 6Eh) as the RXL bit. The RXL signal can be inverted (INVLOS = 1) before driving the open-drain output transistor using the XOR gate provided. Setting  $LOSC = 1$  configures the mux to be controlled by the LOS LO QT alarm. The mux setting (stored in EEPROM) does not take effect until  $VCC > POA$ , allowing the EEPROM to recall.

#### *INX, RSEL, OUTX, RSELOUT*

Digital input pins INX and RSEL primarily serve to meet the rate-select requirements of SFP and SFP+. They can also serve as general-purpose inputs. OUTX and RSELOUT are driven by a combination of the INX, RSEL, and logic dictated by control registers in the EEPROM (see Figure 11). The levels of INX and RSEL can be read from the STATUS register (Lower Memory, Register 6Eh). The open-drain output OUTX can be controlled and/or inverted using the CNFGB register (Table 02h, Register 89h). The open-drain RSELOUT output is software controlled and/or inverted through the STATUS register and

<span id="page-19-0"></span>CNFGA register (Table 02h, Register 88h). External pullup resistors must be provided on OUTX and RSELOUT to realize high logic levels.

#### *FAULT Output*

FAULT can be triggered by all alarms, warnings, and QTs. The six ADC alarms, warnings, and LOS QTs require enabling (Table 01h/05h, Registers F8h and FCh). Latching of the alarms is controlled by the CNFGB and CNFGC registers (Table 02h, Registers 89h*−*8Ah).

#### *Die Identification*

The device has an ID hardcoded in its die. Two registers (Table 02h, Registers 86h*−*87h) are assigned for this feature. Register 86h reads 77h to identify the part as the DS1877; Register 87h reads the present device version.

#### *I2C Communication*

#### *I2C Definitions*

The following terminology is commonly used to describe I2C data transfers.

**Master Device:** The master device controls the slave devices on the bus. The master device generates SCL clock pulses and START and STOP conditions.

**Slave Devices:** Slave devices send and receive data at the master's request.

**Bus Idle or Not Busy:** Time between STOP and START conditions when both SDA and SCL are inactive and in their logic-high states.

**START Condition:** A START condition is generated by the master to initiate a new data transfer with a slave. Transitioning SDA from high to low while SCL remains high generates a START condition. See Figure 12 for applicable timing.

**STOP Condition:** A STOP condition is generated by the master to end a data transfer with a slave. Transitioning SDA from low to high while SCL remains high generates a STOP condition. See Figure 12 for applicable timing.

Repeated START Condition: The master can use a repeated START condition at the end of one data transfer to indicate that it will immediately initiate a new data transfer following the current one. Repeated STARTs are commonly used during read operations to identify a specific memory address to begin a data transfer. A repeated START condition is issued identically to a normal START condition. See Figure 12 for applicable timing.

**Bit Write:** Transitions of SDA must occur during the low state of SCL. The data on SDA must remain valid and unchanged during the entire high pulse



*Figure 12. I2C Timing*

### *SFP Controller for Dual Rx Interface*

<span id="page-20-0"></span>of SCL plus the setup and hold time requirements (Figure 12). Data is shifted into the device during the rising edge of the SCL.

**Bit Read:** At the end of a write operation, the master must release the SDA bus line for the proper amount of setup time (Figure 12) before the next rising edge of SCL during a bit read. The device shifts out each bit of data on SDA at the falling edge of the previous SCL pulse and the data bit is valid at the rising edge of the current SCL pulse. Remember that the master generates all SCL clock pulses, including when it is reading bits from the slave.

Acknowledgement (ACK and NACK): An acknowledgement (ACK) or not-acknowledge (NACK) is always the 9th bit transmitted during a byte transfer. The device receiving data (the master during a read or the slave during a write operation) performs an ACK by transmitting a zero during the 9th bit. A device performs a NACK by transmitting a one during the 9th bit. Timing (Figure 12) for the ACK and NACK is identical to all other bit writes. An ACK is the acknowledgment that the device is properly receiving data. A NACK is used to terminate a read sequence or as an indication that the device is not receiving data.

**Byte Write:** A byte write consists of 8 bits of information transferred from the master to the slave (most significant bit first) plus a 1-bit acknowledgement from the slave to the master. The 8 bits transmitted by the master are done according to the bit write definition and the acknowledgement is read using the bit read definition.

**Byte Read:** A byte read is an 8-bit information transfer from the slave to the master plus a 1-bit ACK or NACK from the master to the slave. The 8 bits of information that are transferred (most significant bit first) from the slave to the master are read by the master using the bit read definition, and the master transmits an ACK using the bit write definition to receive additional data bytes. The master must NACK the last byte read to terminate communication so the slave returns control of SDA to the master.

**Slave Address Byte:** Each slave on the I<sup>2</sup>C bus responds to a slave address byte sent immediately following a START condition. The slave address byte contains the slave address in the most significant 7 bits and the  $R/\overline{W}$  bit in the least significant bit.

The device responds to three slave addresses. The auxiliary memory always responds to a fixed I2C slave address, A0h. (If the main device's slave address is programmed to be A0h/B0h, access to the auxiliary memory is disabled.) The Lower Memory and Tables 00h–05h respond to I2C slave addresses whose lower 3 bits are configurable (A0h*−*AEh, B0h*−*BEh) using the DEVICE ADDRESS byte (Table 02h, Register 8Bh). The user also must set the ASEL bit (Table 02h, Register 88h) for this address to be active. By writing the correct slave address with  $R/\overline{W}$ = 0, the master indicates it writes data to the slave. If  $R/\overline{W}$  = 1, the master reads data from the slave. If an incorrect slave address is written, the device assumes the master is communicating with another I2C device and ignores the communications until the next START condition is sent.

Memory Address: During an I<sup>2</sup>C write operation to the device, the master must transmit a memory address to identify the memory location where the slave is to store the data. The memory address is always the second byte transmitted during a write operation following the slave address byte.

#### *I2C Protocol*

See Figure 13 for an example of I2C timing.

Writing a Single Byte to a Slave: The master must generate a START condition, write the slave address byte ( $R/\overline{W}$  = 0), write the memory address, write the byte of data, and generate a STOP condition. Remember that the master must read the slave's acknowledgement during all byte write operations.

Writing Multiple Bytes to a Slave: To write multiple bytes to a slave, the master generates a START condition, writes the slave address byte  $(R/\overline{W} = 0)$ , writes the memory address, writes up to 8 data bytes, and generates a STOP condition. The device writes 1 to 8 bytes (one page or row) with a single write transaction. This is internally controlled by an address counter that allows data to be written to consecutive addresses without transmitting a memory address before each data byte is sent. The address counter limits the write to one 8-byte page (one row of the memory map). Attempts to write to additional pages of memory without sending a STOP condition between pages result in the address counter wrapping around to the beginning of the present row.

For example: A 3-byte write starts at address 06h and writes three data bytes (11h, 22h, and 33h) to three "consecutive" addresses. The result is that addresses 06h and 07h would contain 11h and 22h, respectively, and the third data byte, 33h, would be written to address 00h.

<span id="page-21-0"></span>

*Figure 13. Example I2C Timing*

To prevent address wrapping from occurring, the master must send a STOP condition at the end of the page, then wait for the bus-free or EEPROM write time to elapse. Then the master can generate a new START condition and write the slave address byte  $(R/\overline{W} = 0)$  and the first memory address of the next memory row before continuing to write data.

**Acknowledge Polling:** Any time a EEPROM page is written, the device requires the EEPROM write time (tWR) after the STOP condition to write the contents of the page to EEPROM. During the EEPROM write time, the device does not acknowledge its slave address because it is busy. It is possible to take advantage of that phenomenon by repeatedly addressing the device, which allows the next page to be written as soon as the device is ready to receive the data. The alternative to acknowledge polling is to wait for maximum period of tWR to elapse before attempting to write again to the device.

EEPROM Write Cycles: When EEPROM writes occur, the device writes the whole EEPROM memory page, even if only a single byte on the page was modified. Writes that do not modify all 8 bytes on the page are allowed and do not corrupt the remaining bytes of memory on the same page. Because the whole page is written, bytes on the page that were not modified during the transaction are still subject to a write cycle. This can result in a whole page being worn out over time by writing a single byte repeatedly. Writing a page 1 byte at a time wears the EEPROM out 8x faster than writing the entire page at once. The device's EEPROM write cycles are specified in the *Nonvolatile Memory Characteristics* table. The specification shown is at the worst-case temperature. It can handle approximately 10x that many writes at room temperature. Writing to SRAM-shadowed EEPROM memory with SEEB = 1 does not count as a EEPROM write cycle when evaluating the EEPROM's estimated lifetime.

### *SFP Controller for Dual Rx Interface*

<span id="page-22-0"></span>Reading a Single Byte from a Slave: Unlike the write operation that uses the memory address byte to define where the data is to be written, the read operation occurs at the present value of the memory address counter. To read a single byte from the slave, the master generates a START condition, writes the slave address byte with  $R/\overline{W} = 1$ , reads the data byte with a NACK to indicate the end of the transfer, and generates a STOP condition.

Manipulating the Address Counter for Reads: A dummy write cycle can be used to force the address pointer to a particular value. To do this, the master generates a START condition, writes the slave address byte ( $R/\overline{W}$  = 0), writes the memory address where it desires to read, generates a repeated START condition, writes the slave address byte (R $\overline{W}$  = 1), reads data with ACK or NACK as applicable, and generates a STOP condition.

#### *Memory Organization*

The device features memory tables that are internally organized into 8-byte rows. The main device located at A2h is used for overall device configuration and receiver 1 control, calibration, alarms, warnings, and monitoring.

Lower Memory, A2h is addressed from 00h*−*7Fh and contains alarm and warning thresholds, flags, masks, several control registers, password entry area (PWE), and the table-select byte.

Table 01h, A2h primarily contains user EEPROM (with PW1 level access) as well as alarm and warning enable bytes.

Table 02h, A2h is a multifunction space that contains configuration registers, scaling and offset values, passwords, and interrupt registers as well as other miscellaneous control bytes.

Table 04h, A2h contains a temperature-indexed LUT for control of the DAC1 voltage. The DAC1 LUT can be programmed in  $2^{\circ}$ C increments over the -40 $^{\circ}$ C to +102 $^{\circ}$ C range. It also contains an LUT for temperature-controlled offsets for DAC1.

Table 05h, A2h is empty by default. It can be configured to contain the alarm and warning enable bytes from Table 01h, Registers F8h*−*FFh with the MASK bit enabled (Table 02h, Register 88h). In this case Table 01h is empty.

The main device located at B2h is used for receiver 2 control, calibration, alarms, warnings, and monitoring.

Lower Memory, B2h is addressed from 00h*−*7Fh and contains alarm and warning thresholds, flags, masks, several control registers, PWE, and the table-select byte.

Table 01h, B2h contains alarm and warning enable bytes.

Table 02h, B2h is a multifunction space that contains configuration registers, scaling and offset values, passwords, interrupt registers as well as other miscellaneous control bytes. Table 02h, B2h only contains functions related to receiver 2. All other functions are controlled by Table 02h, A2h.

Table 04h, B2h contains a temperature-indexed LUT for control of the DAC2 voltage. The DAC2 LUT can be programmed in  $2^{\circ}$ C increments over the -40 $^{\circ}$ C to +102 $^{\circ}$ C range. It also contains an LUT for temperature-controlled offsets for DAC2.

Table 05h, B2h is empty by default. It can be configured to contain the alarm and warning-enable bytes from Table 01h, Registers F8h*−*FFh with the MASK bit enabled (Table 02h, Register 88h). In this case Table 01h is empty.

**Auxiliary Memory (Device A0h)** contains 256 bytes of EE memory accessible from address 00h*−*FFh. It is selected with the device address of A0h.

See the *Register Descriptions* section for a more complete detail of each byte's function, as well as for read/ write permissions for each byte.

<span id="page-23-0"></span>

*Figure 14. Memory Map*

#### *Shadowed EEPROM*

Many nonvolatile memory locations (listed within the *Register Descriptions* section) are actually shadowed EEPROM and are controlled by the SEEB bit in Table 02h, Register 80h.

The device incorporates shadowed EEPROM memory locations for key memory addresses that can be written many times. By default the shadowed EEPROM bit, SEEB, is not set and these locations act as ordinary EEPROM. By setting SEEB, these locations function like SRAM cells, which allow an infinite number of write cycles without concern of wearing out the EEPROM. This also eliminates the requirement for the EEPROM write time, tWR. Because changes made with SEEB enabled do not affect the EEPROM, these changes are not retained through power cycles. The power-on value is the last value written with SEEB disabled. This function can be used to limit the number of EEPROM writes during calibration or to change the monitor thresholds periodically during normal operation helping to reduce the number of times EEPROM is written. Figure 14 shows the memory map and indicates which locations are shadowed EEPROM.

## *SFP Controller for Dual Rx Interface*

#### *Register Descriptions*

<span id="page-24-0"></span>The register maps show each byte/word (2 bytes) in terms of its row in the memory. The first byte in the row is located in memory at the row address (hexadecimal) in the leftmost column. Each subsequent byte on the row is one/two memory locations beyond the previous byte/ word's address. A total of 8 bytes are present on each row. For more information about each of these bytes, see the corresponding register description.

#### *Memory Map Access Codes*

The following section provides the device's register definitions. Each register or row of registers has an access descriptor that determines the password level required to read or write the memory. Level 2 password is intended for the module manufacture access only. Level 1 password allows another level of protection for items the end consumer wishes to protect. Many registers are always readable, but require password access to write. There are a few registers that cannot be read without password access. The following access codes describe each mode the device uses with factory settings for the PW\_ENA and PW\_ENB (Table 02h, Registers C0h–C1h) registers.



#### *Memory Addresses A0h, A2h, and B2h*

There are three separate I2C addresses in the device: A0h, A2h, and B2h. A2h and B2h are used to configure and monitor two receivers. Receiver 1 is accessed using A2h. Receiver 2 is accessed using B2h. Many of the registers in A2h and B2h are shared registers. These registers can be read and written from both A2h and B2h.



#### *Lower Memory Register Map*

<span id="page-25-0"></span>

*<C> or <\_/C> = Common, <D> or <\_/D> = Different, <M> or <\_/M> = Mixture of common and different.*

#### *Table 01h Register Map*



*<C> or <\_/C> = Common, <D> or <\_/D> = Different, <M> or <\_/M> = Mixture of common and different.*

*Note: The ALARM ENABLE bytes (Registers F8h−FFh) can be configured to exist in Table 05h instead of here at Table 01h with the MASK bit (Table 02h, Register 88h). If the row is configured to exist in Table 05h, these locations are empty in Table 01h.*

The access codes represent the factory default values of PW\_ENA and PW\_ENB (Table 02h, Registers C0h*−*C1h). These registers also allow for custom permissions.



## *SFP Controller for Dual Rx Interface*

#### *Table 02h Register Map*

<span id="page-26-0"></span>

*<C> or <\_/C> = Common, <D> or <\_/D> = Different, <M> or <\_/M> = Mixture of common and different.*

\**The final result must be XORed with BB40h before writing to this register.*

#### *Table 04h Register Map*



*<C> or <\_/C> = Common, <D> or <\_/D> = Different, <M> or <\_/M> = Mixture of common and different.*

The access codes represent the factory default values of PW\_ENA and PW\_ENB (Table 02h, Registers C0h*−*C1h). These registers also allow for custom permissions.



#### *Table 05h Register Map*

<span id="page-27-0"></span>

*<C> or <\_/C> = Common, <D> or <\_/D> = Different, <M> or <\_/M> = Mixture of common and different.*

*Note: Table 05h is empty by default. It can be configured to contain the alarm and warning enable bytes from Table 01h, Registers F8h−FFh with the MASK bit enabled (Table 02h, Register 88h). In this case Table 01h is empty.*

#### *Auxiliary Memory A0h Register Map*



*<C> or <\_/C> = Common, <D> or <\_/D> = Different, <M> or <\_/M> = Mixture of common and different.*

The access codes represent the factory default values of PW\_ENA and PW\_ENB (Table 02h, Registers C0h*−*C1h). These registers also allow for custom permissions.



### *SFP Controller for Dual Rx Interface*

*Lower Memory Register Descriptions*

#### <span id="page-28-0"></span>Lower Memory, Register 00h*–*01h: TEMP ALARM HI Lower Memory, Register 04h*–*05h: TEMP WARN HI





Temperature measurement updates above this two's complement threshold set its corresponding alarm or warning bit. Temperature measurement updates equal to or below this threshold clear its alarm or warning bit.

#### Lower Memory, Register 02h*–*03h: TEMP ALARM LO Lower Memory, Register 06h*–*07h: TEMP WARN LO





Temperature measurement updates below this two's complement threshold set its corresponding alarm or warning bit. Temperature measurement updates equal to or above this threshold clear its alarm or warning bit.

#### Lower Memory, Register 08h-09h: V<sub>CC</sub> ALARM HI Lower Memory, Register 0Ch-0Dh: V<sub>CC</sub> WARN HI





Voltage measurement updates above this unsigned threshold set its corresponding alarm or warning bit. Voltage measurements equal to or below this threshold clear its alarm or warning bit.

#### Lower Memory, Register 0Ah-0Bh: V<sub>CC</sub> ALARM LO Lower Memory, Register 0Eh-0Fh: V<sub>CC</sub> WARN LO



W2 or (PW1 and WLOWER) ommon A2h and B2h memory locations onvolatile (SEE)



Voltage measurement updates below this unsigned threshold set its corresponding alarm or warning bit. Voltage measurements equal to or above this threshold clear its alarm or warning bit.

#### Lower Memory, Register 10h*–*1Fh: EE





PW2 level access-controlled EEPROM.

## *SFP Controller for Dual Rx Interface*

#### Lower Memory, Register 20h*–*21h: RSSI ALARM HI Lower Memory, Register 24h*–*25h: RSSI WARN HI





Voltage measurement updates above this unsigned threshold set its corresponding alarm or warning bit. Voltage measurements equal to or below this threshold clear its alarm or warning bit.

#### Lower Memory, Register 22h*–*23h: RSSI ALARM LO Lower Memory, Register 26h*–*27h: RSSI WARN LO





Voltage measurement updates below this unsigned threshold set its corresponding alarm or warning bit. Voltage measurements equal to or above this threshold clear its alarm or warning bit.

#### Lower Memory, Register 28h*–*37h: EE





PW2 level access-controlled EEPROM.

#### Lower Memory, Register 38h*–*4Fh: EE





PW2 level access-controlled EEPROM.

#### Lower Memory, Register 50h*–*5Fh: EE





PW2 level access-controlled EEPROM.

## *SFP Controller for Dual Rx Interface*

#### Lower Memory, Register 60h*–*61h: TEMP VALUE





Signed two's complement direct-to-temperature measurement.

#### Lower Memory, Register 62h-63h: V<sub>CC</sub> VALUE





Left-justified unsigned voltage measurement.

#### Lower Memory, Register 64h*–*67h: RESERVED





These registers are reserved. The value when read is 00h.

#### Lower Memory, Register 68h*–*69h: RSSI VALUE





Left-justified unsigned voltage measurement.

#### Lower Memory, Register 6Ah*–*6Dh: RESERVED



These registers are reserved. The value when read is 00h.

## *SFP Controller for Dual Rx Interface*

#### Lower Memory, Register 6Eh: STATUS







#### Lower Memory, Register 6Fh: UPDATE







#### Lower Memory, Register 70h: ALARM3







## *SFP Controller for Dual Rx Interface*

#### Lower Memory, Register 71h: ALARM2



#### Lower Memory, Register 72h: RESERVED



This register is reserved.

#### Lower Memory, Register 73h: ALARM0



73h LOS HI LOS LO RESERVED RESERVED RESERVED RESERVED RESERVED RESERVED BIT 7 BIT 0 BIT 0



#### Lower Memory, Register 74h: WARN3







### *SFP Controller for Dual Rx Interface*

#### Lower Memory, Registers 75h*–*7Ah: RESERVED



These registers are reserved. The value when read is 00h.

#### Lower Memory, Registers 7Bh*–*7Eh: PASSWORD ENTRY (PWE)





There are two passwords for the device. Each password is 4 bytes long. The lower level password (PW1) has all the access of a normal user plus those made available with PW1. The higher level password (PW2) has all the access of PW1 plus those made available with PW2. The values of the passwords reside in EEPROM inside PW2 memory. At power-up, all PWE bits are set to 1. All reads at this location are 0.

#### Lower Memory, Register 7Fh: TABLE SELECT (TBL SEL)





The upper memory tables of the device are accessible by writing the desired table value in this register. The poweron value of this register is defined by the value written to TBLSELPON (Table 02h, Register C7h).

#### *Table 01h Register Descriptions*

#### <span id="page-39-0"></span>Table 01h, Register 80h*–*F7h: EEPROM





EEPROM for PW1 and/or PW2 level access.

#### Table 01h, Register F8h: ALARM EN3



BIT 7 BIT 0 BI

Layout is identical to ALARM<sub>3</sub> in Lower Memory, Register 70h. Enables alarms to create FLTINT (Lower Memory, Register 71h) logic. The MASK bit (Table 02h, Register 88h) determines whether this memory exists in Table 01h or 05h.



## *SFP Controller for Dual Rx Interface*

#### Table 01h, Register F9h: ALARM EN2



BIT 7 BIT 0

Layout is identical to ALARM2 in Lower Memory, Register 71h. Enables alarms to create FLTINT (Lower Memory, Register 71h). The MASK bit (Table 02h, Register 88h) determines whether this memory exists in Table 01h or 05h.



#### Table 01h, Register FAh: RESERVED



This register is reserved.

#### Table 01h, Register FBh: ALARM EN0





Layout is identical to ALARM0 in Lower Memory, Register 73h. The MASK bit (Table 02h, Register 88h) determines whether this memory exists in Table 01h or 05h.



#### Table 01h, Register FCh: WARN EN3





Layout is identical to WARN3 in Lower Memory, Register 74h. Enables warnings to create FLTINT (Lower Memory, Register 71h) logic. The MASK bit (Table 02h, Register 88h) determines whether this memory exists in Table 01h or 05h.



## *SFP Controller for Dual Rx Interface*

#### <span id="page-42-0"></span>Table 01h, Register FDh*–*FFh: RESERVED



These registers are reserved.

#### *Table 02h Register Descriptions*

#### Table 02h, Register 80h: MODE







#### Table 02h, Register 81h: TEMPERATURE INDEX (TINDEX)





Holds the calculated index based on the temperature measurement. This index is used for the address during lookup of Table 04h. Temperature measurements below -40°C or above +102°C are clamped to 80h and C7h, respectively. The calculation of TINDEX is as follows:

$$
TINDER = \frac{Temp\_Value + 40°C}{2°C} + 80h
$$

For the temperature-indexed LUTs ( $2^{\circ}$ C), the index used during the lookup function for each table is as follows:



For the 8-position LUT tables, the following table shows the lookup function:



#### Table 02h, Register 82h*–*85h: RESERVED



These registers are reserved.

#### Table 02h, Register 86h: DEVICE ID



BIT 7 BIT 0

Hardwired connections to show the device ID.

## *SFP Controller for Dual Rx Interface*

#### Table 02h, Register 87h: DEVICE VER



87h DEVICE VERSION

BIT 7 BIT 0 BIT

Hardwired connections to show the device version.

#### Table 02h, Register 88h: CNFGA







#### Table 02h, Register 89h: CNFGB







### *SFP Controller for Dual Rx Interface*

#### Table 02h, Register 8Ah: CNFGC







#### Table 02h, Register 8Bh: DEVICE ADDRESS





This value becomes the I2C slave address for the main memory when the ASEL bit (Table 02h, Register 88h) is set. If A0h/B0h is programmed to this register, the auxiliary memory is disabled. For example, writing xxxx\_010x makes the main device addresses A4h and B4h.

#### Table 02h, Register 8Ch: RESERVED



This register is reserved.

#### Table 02h, Register 8Dh: FORCE RSSI







### *SFP Controller for Dual Rx Interface*

#### Table 02h, Register 8Eh: RIGHT-SHIFT2 (RSHIFT2)



BIT 7 BIT 0 BIT

Allows for right-shifting the final answer of RSSI2 COARSE and RSSI2 FINE. This allows for scaling the measurement to the smallest full-scale voltage and then right-shifting the final result so the reading is weighted to the correct LSB.

#### Table 02h, Register 8Fh: RIGHT-SHIFT1 (RSHIFT1)





Allows for right-shifting the final answer of RSSI1 COARSE and RSSI1 FINE. This allows for scaling the measurements to the smallest full-scale voltage and then right-shifting the final result so the reading is weighted to the correct LSB.

#### Table 02h, Register 90h*–*91h: RESERVED



These registers are reserved.

Table 02h, Register 92h-93h: V<sub>CC</sub> SCALE Table 02h, Register 94h*–*95h: XOVER2 COARSE Table 02h, Register 96h*–*97h: XOVER2 FINE Table 02h, Register 98h*–*99h: RSSI2 COARSE SCALE Table 02h, Register 9Ah*–*9Bh: RSSI2 FINE SCALE Table 02h, Register 9Ch*–*9Dh: RSSI1 COARSE SCALE Table 02h, Register 9Eh*–*9Fh: RSSI1 FINE SCALE



Controls the scaling or gain of the full-scale voltage measurements. The factory-calibrated value produces an FS voltage of 6.5536V for Vcc, 2.5V for RSSI2 COARSE and RSSI1 COARSE, and 0.3125V for RSSI2 FINE and RSSI1 FINE.

#### Table 02h, Register A0h*–*A1h: INTERNAL TEMP OFFSET





Allows for offset control of temperature measurement if desired. The final result must be XORed with BB40h before writing to this register. Factory calibration contains the desired value for a reading in degrees Celsius.

### *SFP Controller for Dual Rx Interface*

Table 02h, Register A2h-A3h: V<sub>CC</sub> OFFSET Table 02h, Register A4h*–*A5h: XOVER1 COARSE Table 02h, Register A6h*–*A7h: XOVER1 FINE Table 02h, Register A8h*–*A9h: RSSI2 COARSE OFFSET Table 02h, Register AAh*–*ABh: RSSI2 FINE OFFSET Table 02h, Register ACh*–*ADh: RSSI1 COARSE OFFSET Table 02h, Register AEh*–*AFh: RSSI1 FINE OFFSET FACTORY DEFAULT 00h



Allows for offset control of these voltage measurements if desired. This number is two's complement.

#### Table 02h, Register B0h*–*B3h: PW1





The PWE value is compared against the value written to this location to enable PW1 access. At power-on, the PWE value is set to all ones. Thus, writing these bytes to all ones grants PW1 access on power-on without writing the password entry. All reads of this register are 00h.

#### Table 02h, Register B4h*–*B7h: PW2





The PWE value is compared against the value written to this location to enable PW2 access. At power-on, the PWE value is set to all ones. Thus, writing these bytes to all ones grants PW2 access on power-on without writing the password entry. All reads of this register are 00h.

## *SFP Controller for Dual Rx Interface*

#### Table 02h, Register B8h: LOS RANGING2





This register controls the full-scale range of the QT monitoring for the RSSI2 differential inputs.



#### Table 02h, Register B9h: RESERVED



This register is reserved.

#### Table 02h, Register BAh: HLOS2





Fast comparison DAC threshold adjust for high LOS2. The combination of HLOS2 and LLOS2 creates a hysteresis comparator. As RSSI2 falls below the LLOS2 threshold, the LOS2 LO alarm bit is set to 1. The LOS2 LO alarm remains set until the RSSI2 input is found above the HLOS2 threshold setting, which clears the LOS2 LO alarm bit and sets the LOS2 HI alarm bit.

#### Table 02h, Register BBh: LLOS2





Fast comparison DAC threshold adjust for low LOS2. See HLOS2 (Table 02h, Register BAh) for the functional description.

## *SFP Controller for Dual Rx Interface*

#### Table 02h, Register BCh: LOS RANGING1





This register controls the full-scale range of the QT monitoring for the RSSI1 differential inputs.



#### Table 02h, Register BDh: RESERVED



This register is reserved.

#### Table 02h, Register BEh: HLOS1





Fast comparison DAC threshold adjust for high LOS1. The combination of HLOS1 and LLOS1 creates a hysteresis comparator. As RSSI1 falls below the LLOS1 threshold, the LOS1 LO alarm bit is set to 1. The LOS1 LO alarm remains set until the RSSI1 input is found above the HLOS1 threshold setting, which clears the LOS1 LO alarm bit and sets the LOS1 HI alarm bit.

#### Table 02h, Register BFh: LLOS1



BIT 7 BIT 0 BIT 0

BFh 2<sup>7</sup> 26 25 24 23 2<sup>2</sup> 2<sup>2</sup> 21 20

Fast comparison DAC threshold adjust for low LOS1. See HLOS1 (Table 02h, Register BEh) for the functional description.

## *SFP Controller for Dual Rx Interface*

#### Table 02h, Register C0h: PW\_ENA







#### Table 02h, Register C1h: PW\_ENB







## *SFP Controller for Dual Rx Interface*

#### Table 02h, Register C2h*–*C5h: RESERVED



These registers are reserved.

#### Table 02h, Register C6h: POLARITY







#### Table 02h, Register C7h: TBLSELPON



Chooses the initial value for the TBL SEL byte (Lower Memory, Register 7Fh) at power-on.

#### Table 02h, Register C8h*–*C9h: DAC2 VALUE





The digital value used for DAC2 VALUE. It is the result of LUT4 plus DAC2 OFFSET times 4 recalled from Address B0h, Table 04h (Registers F8h–FFh) at the adjusted memory address found in TINDEX. This register is updated at the end of the temperature conversion.

DAC2 VALUE = LUT4 + DAC2 OFFSET x 4

$$
V_{DAC2} = \frac{V_{REFIN}}{1024} \times DAC2 \text{ VALUE}_{d} \text{ (if POLARITY = 0)}
$$

$$
V_{DAC2} = V_{REFIN} - \frac{V_{REFIN}}{1024} \times DAC \text{ VALUE}_{d} \text{ (if POLARITY = 1)}
$$

#### Table 02h, Register CAh*–*CBh: RESERVED



These registers do not exist.

## *SFP Controller for Dual Rx Interface*

#### Table 02h, Register CCh*–*CDh: DAC1 VALUE





The digital value used for DAC1 VALUE. It is the result of LUT4 plus DAC1 OFFSET times 4 recalled from Address A0h, Table 04h (Registers F8h–FFh) at the adjusted memory address found in TINDEX. This register is updated at the end of the temperature conversion.

DAC1 VALUE = LUT4 + DAC1 OFFSET x 4

$$
V_{DAC1} = \frac{V_{REFIN}}{1024} \times DAC1 \text{ VALUE}_{d} \text{ (if POLARITY = 0)}
$$

$$
V_{DAC1} = V_{REFIN} - \frac{V_{REFIN}}{1024} \times DAC1 \text{ VALUE}_{d} \text{ (if POLARITY = 1)}
$$

#### Table 02h, Register CEh*–*CFh: RESERVED



These registers do not exist.

#### Table 02h, Register D0h*–*FFh: EMPTY



These registers do not exist.

#### *Table 04h Register Descriptions*

#### <span id="page-61-0"></span>Table 04h, Register 80h*–*C7h: DAC LUT



Digital value for the DAC1 VALUE (A2h address) and DAC2 VALUE (B2h address) outputs. The DAC LUT is a set of registers assigned to hold the temperature profile for the DAC1 and DAC2 values. The temperature measurement is used to index the LUT (TINDEX, Table 02h, Register 81h) in 2°C increments from -40°C to +102°C, starting at 80h. Register 80h defines the -40°C to -38°C DAC output, Register 81h defines -38°C to -36°C DAC output, and so on. Values recalled from this EEPROM memory table are written into the DAC1 and DAC2 value (Table 02h, Registers C8h–C9h, CCh–CDh) locations that hold the values until the next temperature conversion. The device can be placed into a manual mode (DAC1EN and DAC2EN bits, Table 02h, Register 80h), where DAC1 and DAC2 values are directly controlled for calibration. If the temperature compensation functionality is not required, program the entire table to the desired modulation setting.

#### Table 02h, Register C8h*–*F7h: EMPTY



These registers do not exist.

## *SFP Controller for Dual Rx Interface*

#### <span id="page-62-0"></span>Table 04h, Register F8h*–*FFh: DAC OFFSET LUT





The digital value for the temperature offset of the DAC1 and DAC2 VALUE outputs.



The DAC VALUE is a 10-bit value. The DAC LUT is an 8-bit LUT. The DAC OFFSET LUT times 4 plus the DAC LUT makes use of the entire 10-bit range.

#### Auxiliary Memory A0h, Register 00h*–*7Fh: EEPROM

#### *Auxiliary Memory A0h Register Descriptions*



00h–7Fh | 2<sup>7</sup> | 2<sup>6</sup> | 2<sup>5</sup> | 2<sup>4</sup> | 2<sup>3</sup> | 2<sup>2</sup> | 2<sup>1</sup> | 2<sup>0</sup>

BIT 7 BIT 0 BIT 0

Accessible with the slave address A0h.

#### <span id="page-63-0"></span>Auxiliary Memory A0h, Register 80h*–*FFh: EEPROM



PW2 or (PW1 and WAUXB) or WAUXBU Nonvolatile (EE)



Accessible with the slave address A0h.

### *Applications Information*

#### *Power-Supply Decoupling*

To achieve best results, it is recommended that the power supply is decoupled with a  $0.01\mu$ F or a  $0.1\mu$ F capacitor. Use high-quality, ceramic, surface-mount capacitors, and mount the capacitors as close as possible to the V<sub>CC</sub> and GND pins to minimize lead inductance.

#### *SDA and SCL Pullup Resistors*

SDA is an open-collector output on the device that requires a pullup resistor to realize high logic levels. A master using either an open-collector output with a pullup resistor or a push-pull output driver can be used for SCL. Pullup resistor values should be chosen to ensure that the rise and fall times listed in the *I2C AC Electrical Characteristics* table are within specification.

 *Package Information*

For the latest package outline information and land patterns, go to **<www.maximintegrated.com/packages>**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.



## *SFP Controller for Dual Rx Interface*

#### *Revision History*

<span id="page-64-0"></span>



Maxim Integrated cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim Integrated product. No circuit patent licenses are implied. Maxim Integrated reserves the right to change the circuitry and specifications without notice at any time. The parametric values (min and *max limits) shown in the Electrical Characteristics table are guaranteed. Other parametric values quoted in this data sheet are provided for guidance.*

#### *Maxim Integrated 160 Rio Robles, San Jose, CA 95134 USA 1-408-601-1000* 65

© 2010 Maxim Integrated Products, Inc. Maxim Integrated and the Maxim Integrated logo are trademarks of Maxim Integrated Products, Inc.

## **Mouser Electronics**

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Analog Devices Inc.](https://www.mouser.com/maxim-integrated): [DS1877T+](https://www.mouser.com/access/?pn=DS1877T+) [DS1877T+T&R](https://www.mouser.com/access/?pn=DS1877T+T&R)